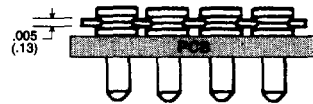
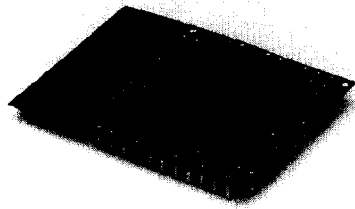
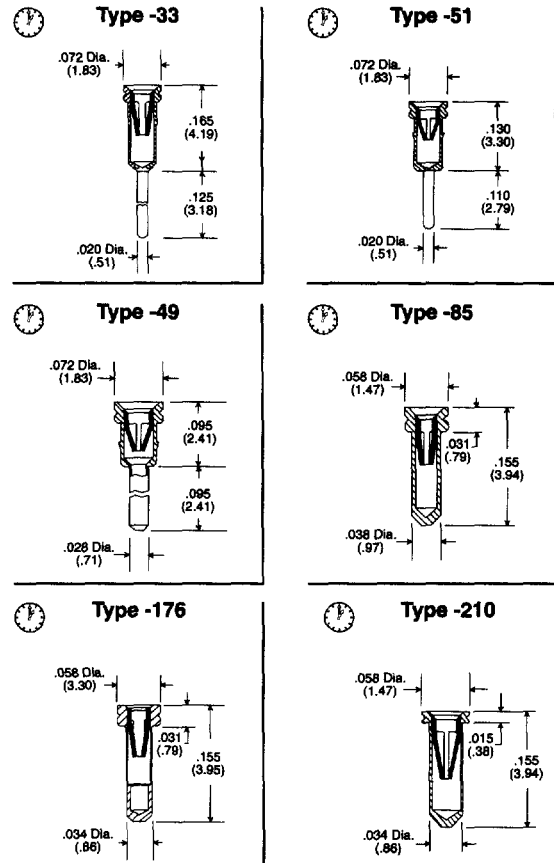


Peel-A-Way® Low Insertion Force PGA Sockets



Terminal Information



Features:

- Disposable carriers peel away after soldering.
- Peel-A-Way® tabs and full grid wafer supplied on all Peel-A-Way® PGA sockets.
- Maximum air flow under PGA for greater cooling.
- Better flux rinse and cleaning.
- Allows inspection of solder joints on both sides of PCB.
- Lowest profile with use of type -210 terminal.
- Peel-A-Way® disposable socket terminal carrier available in any configuration shown or custom designed to meet your specifications.

Terminals and Contacts:

Terminal: Brass - Copper Alloy 360, ASTM-B-16

Contact: Beryllium Copper - Copper Alloy 172, ASTM-B-194

Plating:

Terminal: Tin-Lead over Nickel

Contact: Gold over Nickel

Gold per MIL-G-45204

Tin-Lead per MIL-P-81728

Nickel per QQ-N-290

Body Material:

KS/KIS - Polyimide Film

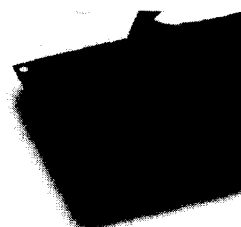
-269°C to 400°C (-452°F to 752°F)

Quick turn delivery available on standard terminal types. Additional terminal types available.

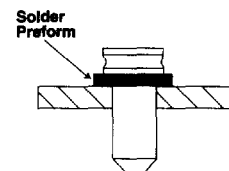
Socket Options



RTV Sealed - Pg. 27



Tape Sealed - Pg. 27

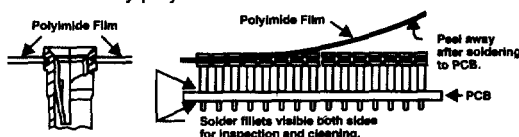


Solder Preform - Pg. 26

See designated pages for how to order information on these socket options.

How To Use:

1. Place socket in PCB.
2. Send PCB and socket through soldering operation.
3. Peel away polyimide film carrier.



How To Order

